

Statement of Compliance.

Restriction of Hazardous Substances (ROHS): Directive 2002/95/EC.

All semiconductor products assembled in "lead-free" packages provided by ASAHI KASEI MICRODEVICES CORPORATION are fully compliant with RoHS.

These lead-free version products:

- Contain less than 1000 ppm of Pb, Hg, Cr+6 PBB and PBDE, and less than 100 ppm of Cd.
None of these substances is intentionally included at concentration.
- Have outer lead plating that contains less than 1000 ppm of Pb, and no intentionally included Pb.

ASAHI KASEI MICRODEVICES CORPORATION can provide copies of analysis data of the measurement used in assembly for each of these products upon request.

Note ROHS compliant products from ASAHI KASEI MICRODEVICES CORPORATION are identified with "Pb free" letter indication on the product label posted on the anti-static shield bag and the inner box.

December 2009